SWITCHMODE™ Power Rectifier 100 V, 30 A

Features and Benefits

- Low Forward Voltage: 0.67 V @ 125°C
- Low Power Loss/High Efficiency
- High Surge Capacity
- 175°C Operating Junction Temperature
- 30 A Total (15 A Per Diode Leg)
- Guard-Ring for Stress Protection
- Pb-Free Package is Available

Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 Units Per Plastic Tube

MAXIMUM RATINGS

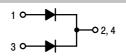
Please See the Table on the Following Page

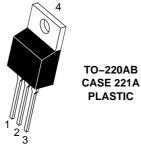


ON Semiconductor®

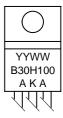
http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 30 AMPERES 100 VOLTS





MARKING DIAGRAM



YY = Year WW = Work Week B30H100 = Device Code AKA = Polarity Designator

ORDERING INFORMATION

Device	Package	Shipping
MBR30H100CT	TO-220	50 Units/Rail
MBR30H100CTG	TO-220 (Pb-Free)	50 Units/Rail

MAXIMUM RATINGS (Per Diode Lea)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V
Average Rectified Forward Current (Rated V_R) $T_C = 155$ °C	I _{F(AV)}	15	А
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz) T _C = 150°C	I _{FRM}	30	Α
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	250	А
Operating Junction Temperature (Note 1)	T _J	+175	°C
Storage Temperature	T _{stg}	-65 to +175	°C
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs
Controlled Avalanche Energy (see test conditions in Figures 10 and 11)	W _{AVAL}	200	mJ
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V
HERMAL CHARACTERISTICS			
Maximum Thermal Resistance – Junction–to–Case – Junction–to–Ambient	R _{θJC} R _{θJA}	2.0 60	°C/W
ELECTRICAL CHARACTERISTICS (Per Diode Leg)			
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} &(I_F=15 \text{ A}, T_C=25^{\circ}\text{C}) \\ &(I_F=15 \text{ A}, T_C=125^{\circ}\text{C}) \\ &(I_F=30 \text{ A}, T_C=25^{\circ}\text{C}) \\ &(I_F=30 \text{ A}, T_C=125^{\circ}\text{C}) \end{aligned} $	V _F	0.80 0.67 0.93 0.80	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 125^{\circ}C$) (Rated DC Voltage, $T_C = 25^{\circ}C$)	i _R	6.0 0.0045	mA

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.
- 2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

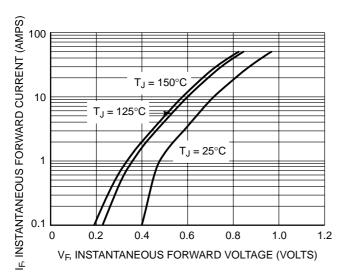


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

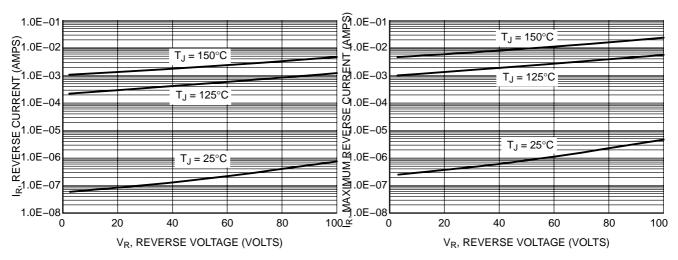


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

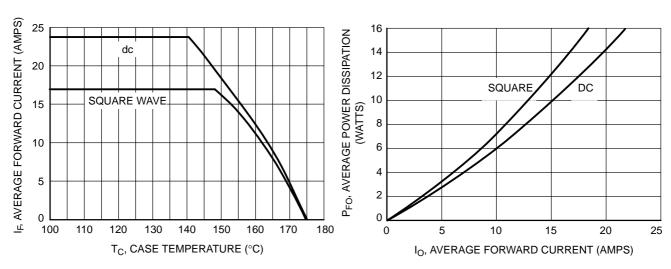


Figure 5. Current Derating

Figure 6. Forward Power Dissipation

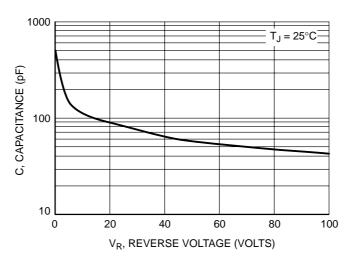


Figure 7. Capacitance

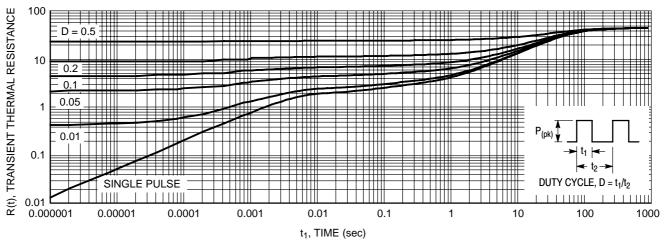


Figure 8. Thermal Response Junction-to-Ambient

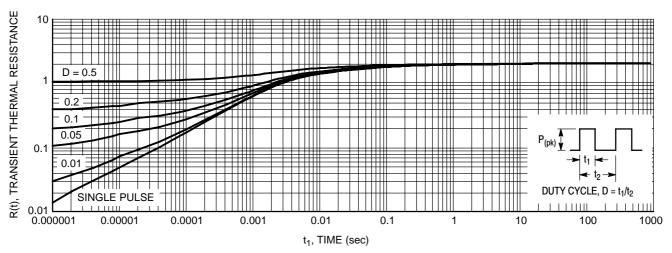


Figure 9. Thermal Response Junction-to-Case

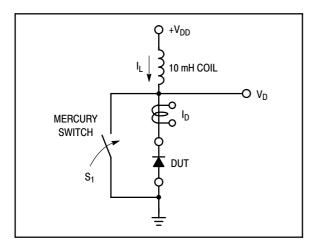


Figure 10. Test Circuit

The unclamped inductive switching circuit shown in Figure 10 was used to demonstrate the controlled avalanche capability of this device. A mercury switch was used instead of an electronic switch to simulate a noisy environment when the switch was being opened.

When S_1 is closed at t_0 the current in the inductor I_L ramps up linearly; and energy is stored in the coil. At t_1 the switch is opened and the voltage across the diode under test begins to rise rapidly, due to di/dt effects, when this induced voltage reaches the breakdown voltage of the diode, it is clamped at BV_{DUT} and the diode begins to conduct the full load current which now starts to decay linearly through the diode, and goes to zero at t_2 .

By solving the loop equation at the point in time when S_1 is opened; and calculating the energy that is transferred to the diode it can be shown that the total energy transferred is equal to the energy stored in the inductor plus a finite amount of energy from the V_{DD} power supply while the diode is in breakdown (from t_1 to t_2) minus any losses due to finite component resistances. Assuming the component resistive

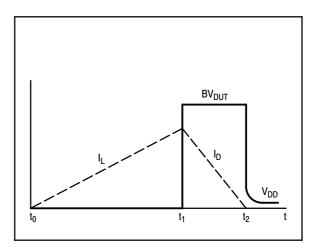


Figure 11. Current-Voltage Waveforms

elements are small Equation (1) approximates the total energy transferred to the diode. It can be seen from this equation that if the V_{DD} voltage is low compared to the breakdown voltage of the device, the amount of energy contributed by the supply during breakdown is small and the total energy can be assumed to be nearly equal to the energy stored in the coil during the time when S_1 was closed, Equation (2).

EQUATION (1):

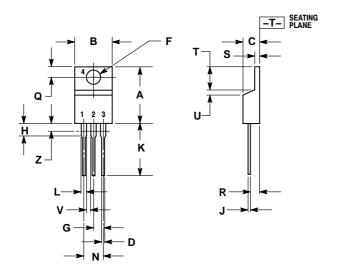
$$W_{AVAL} \approx \frac{1}{2}LI_{LPK}^{2} \left(\frac{BV_{DUT}}{BV_{DUT} - V_{DD}} \right)$$

EQUATION (2):

$$W_{AVAL} \approx \frac{1}{2}LI_{LPK}^2$$

PACKAGE DIMENSIONS

TO-220 PLASTIC CASE 221A-09 ISSUE AA



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14 5M 1982
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

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